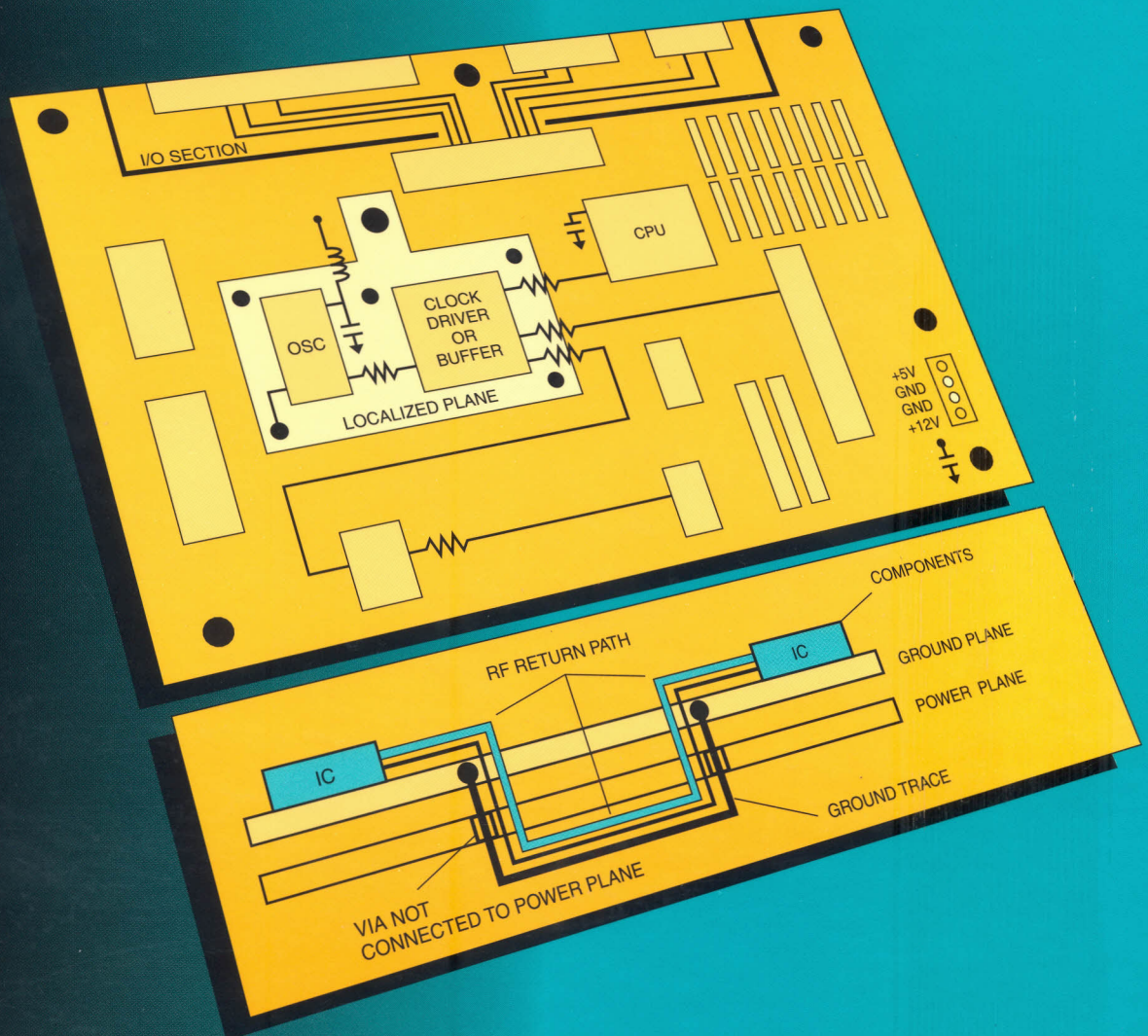


PRINTED CIRCUIT BOARD DESIGN TECHNIQUES FOR EMC COMPLIANCE

SECOND EDITION

A Handbook for Designers

MARK I. MONTROSE



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